Electronic Acknowledgement Receipt				
EFS ID:	1269572			
Application Number:	10824111			
International Application Number:				
Confirmation Number:	6146			
Title of Invention:	Wafer-level electronic modules with integral connector contacts and methods of fabricating the same			
First Named Inventor/Applicant Name:	Seung Duk Baek			
Customer Number:	20792			
Filer:	Robert M. Meeks/Candi Riggs			
Filer Authorized By:	Robert M. Meeks			
Attorney Docket Number:	5649-1279			
Receipt Date:	24-OCT-2006			
Filing Date:	14-APR-2004			
Time Stamp:	10:51:11			
Application Type:	Utility			

## Payment information:

Submitted with Payment	no
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## File Listing:

Document Number	Document Description	File Name	File Size(Bytes)	Multi Part /.zip	Pages (if appl.)
1		Amendment.pdf	642872	yes	11

	Multipart Description/PDF files in .zip description			
	Document Description	Start	End	
	Amendment - After Non-Final Rejection	1	1	
	Claims	2	7	
	Applicant Arguments/Remarks Made in an Amendment	8	11	
Warnings:				
Indiana the second				

Information:

Total Files Size (in bytes): 642872

This Acknowledgement Receipt evidences receipt on the noted date by the USPTO of the indicated documents, characterized by the applicant, and including page counts, where applicable. It serves as evidence of receipt similar to a Post Card, as described in MPEP 503.

## New Applications Under 35 U.S.C. 111

If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

## National Stage of an International Application under 35 U.S.C. 371

If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.